Product Change Notification

Change Notification #:	**115935 - 01**
Change Title:	**Intel® Ethernet Server Adapter I340-T2, Product Code: E1G42HTG1P20, MM#904277** **Intel® Ethernet Server Adapter I340-T4, Product Code: E1G44HTG1P20, MM#904267, Product Code:E1G44HTBLK, MM#904223, Product Code: E1G44HT, MM#904198** **Intel® Ethernet SDI Adapter FM10420-100GbE-QDA2, Product Code: FM10420QDA2G1P5, MM#947651** **Intel® Ethernet OCP Server Adapter X520-DA1 (NCSI), Product Code: X520DA1OCPG2P20, MM#934017** **Intel® Ethernet OCP Server Adapter X520-DA2 (NCSI) Product Code: X520DA2OCPG2P20, MM#934018** **PCN 115935-01, Label,** **Label Update** **Reason for Revision: Updating new OUI Block in description of change.**
Date of Publication:	**November 27, 2017**

Key Characteristics of the Change:

Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Dec 15, 2017

Reason for Revision: Updating new OUI Block in description of change.

Description of Change to the Customer:

The Intel products listed in the Products affected table will undergo the following changes:

1. The OUI Block 90-E2-BA has hit a low water mark, the new OUI Block used will be **68-05-CA**.
2. The Taiwan BSMI has a new RoHS declaration and inspection mark.

The BSMI logo will be updated on the board level, with a cover up label, and on the packaging label if it currently exists there.

Current:	New:
D33025	D33025 RoHS

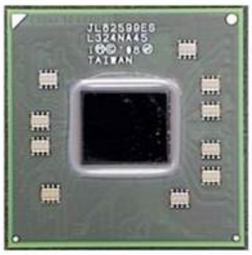
3. Ukraine has a new RoHS declaration that will be added to the outer box packaging label.

4. In order to align all our products and labels with the JEDEC 609A Standard for board assembly marking, we will remove the HF or LF (as applicable) from all outer box packaging labels if it currently exists there.

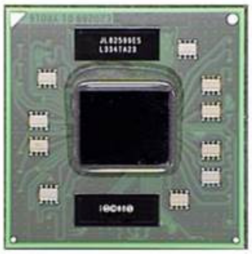
Before			**After**
Pb 2nd lvl intct HF–e1/e1	O	Pb 2nd lvl intct LF–e1/e1	Pb 2nd lvl intct e1/e1

The Intel products with Product Code: X520DA1OCPG2P20, MM#934017 and Product Code: X520DA2OCPG2P20, MM#934018 will undergo the additional change:

- As per the Intel Corporate Green Initiative, Intel is moving its products to a RoHS Compliant 100% lead-free process which impacted several of the flip-chip silicon product lines. The current silicon products are listed as 'exempt' based on the EU RoHS exemption for FLI leaded parts. This change removed that RoHS exemption. There is no impact on the silicon's function, electrical performance, mechanical use or stated reliability. Intel has qualified and certified this change in the same way as all products supplied to our customers. There is no form-fit-function change for any of the impacted silicon. FLI (First Level Interconnect) material will change from Lead (Pb) based solder bump technology to Pb-Free (Sn/Ag) technology. There is no change to the second level interconnects for these products. This change affects First Level Interconnects only. The transition from eutectic to lead free at the FLI style of the product marking will change. The mark will go to a laser mark on swatch versus an ink stamp on substrate as illustrated below.



Niantic Eutectic (Pb-bumps)



Niantic Lead-free

As a result of these changes, the PBA (printed board assembly) and TA (top assembly) numbers will roll as noted in the affected products table within this PCN. If the PBA/TA numbers are printed on any product or box labels, those will show the PBA/TA dash roll as well.

Customer Impact of Change and Recommended Action: Intel anticipates no impact to customers. The customer can expect to receive mixed inventory.

Please contact your local Intel Field Sales Rep if you have any further questions about these change

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
E1G44HT	904198	E76877-008	E84075-008	E76877-009	E84075-009
E1G44HTBLK	904223	E80225-008	E84075-008	E80225-009	E84075-009
E1G44HTG1P20	904267	E80231-010	E68891-020	E80231-011	E68891-021
E1G42HTG1P20	904277	E80235-006	E79938-014	E80235-007	E79938-015
X520DA1OCPG2P20	934017	H35858-003	H31655-004	H35858-004	H31655-005
X520DA2OCPG2P20	934018	H35864-003	H31656-004	H35864-004	H31656-005
FM10420QDA2G1P5	947651	J14583-001	J19406-003	J14583-002	J19406-004

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
November 27, 2017	00	Originally Published PCN
January 12, 2018	01	Updating new OUI Block in description of change.

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115935 - 01

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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